Product data sheet

1. General description

EEPP[™] - Efficiency Enhanced Pt Planar rectifier in a TO247-2L plastic package.

2. Features and benefits

- · Fast switching
- · Reduces switching losses with improved lower reverse recovery charge
- · Soft recovery characteristics
- · Low thermal resistance
- · Low leakage current
- · Planar termination structure
- High operating temperature capability (T_{i(max)} = 175°C)
- Higher I_{FSM} capability

3. Applications

- Switched-Mode Power Supplies
- Power factor correction diode
- · Uninterrupted Power Supply

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions Values			Unit		
Absolute maximum rating							
V_{RRM}	repetitive peak reverse voltage			12	.00		V
I _{F(AV)}	average forward current	$δ = 0.5$; square-wave pulse; $T_{mb} \le 75$ °C; Fig. 1; Fig. 2; Fig. 3	75			А	
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t_p = 25 μs; $T_{mb} \le 75$ °C; square-wave pulse	150			А	
I _{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	600			Α	
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse	660			Α	
Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Static ch	aracteristics						
V _F	forward voltage	I _F = 75 A; T _j = 25 °C; <u>Fig. 6</u>		-	2.8	3.3	V
		I _F = 75 A; T _j = 150 °C; <u>Fig. 6</u>		-	2.2	-	V
Dynamic	characteristics						
t _{rr}	reverse recovery time	$I_F = 1 \text{ A}$; $V_R = 30 \text{ V}$; $dI_F/dt = 100 \text{ A/}\mu\text{s}$; $T_j = 25 \text{ °C}$; Fig. 7		-	-	85	ns
Avalanch	Avalanche energy						
E _{AS}	non-repetitive avalanche energy	$I_R = 1.6 \text{ A}; T_{j(init)} = 25 \text{ °C}; L = 40 \text{ mH}$		50	-	-	mJ

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		1/ 1/4 A
2	Α	anode		K — A 001aaa020
mb	mb	mounting base; connected to cathod	o K A TO247-2L	

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity		Package issue date
BYC75W-1200P	TO247-2L	BYC75W-1200PQ	Tube	30	TO247A-2L	22-Jun-2017

7. Marking

Table 4. Marking codes

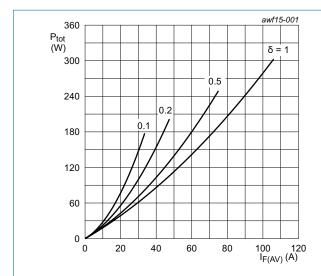
Type number	Marking codes
BYC75W-1200P	BYC75W 1200P

8. Limiting values

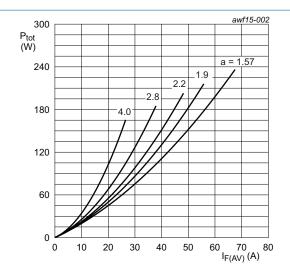
Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		1200	V
V_{RWM}	crest working reverse voltage		1200	V
V_R	reverse voltage	DC	1200	V
I _{F(AV)}	average forward current	$δ$ = 0.5; square-wave pulse; $T_{mb} \le 75$ °C; Fig. 1; Fig. 2; Fig. 3	75	А
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _{mb} ≤ 75 °C; square-wave pulse	150	А
I _{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4	600	А
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse	660	А
T _{stg}	storage temperature		-55 to 175	°C
T _j	junction temperature		-55 to 175	°C



$$\begin{split} & |_{\text{F(AV)}} = |_{\text{F(RMS)}} \times \sqrt{\delta} \\ & |_{\text{V}_{\text{o}}} = 1.727 \text{ V; R}_{\text{s}} = 0.0106 \ \Omega \end{split}$$
 Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



a = form factor = $I_{F(RMS)}/I_{F(AV)}$ V_o = 1.727 V; R_s = 0.0106 Ω

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

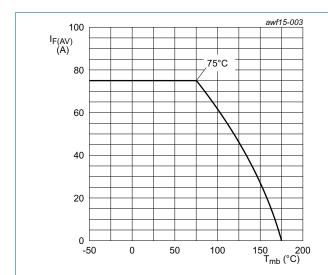


Fig. 3. Forward current as a function of mounting base temperature; typical values

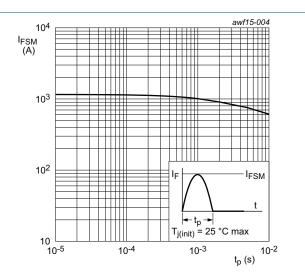


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{\text{th(j-mb)}}$	thermal resistance from junction to mounting base	Fig. 5	-	-	0.4	K/W
$R_{\text{th(j-a)}}$	thermal resistance from junction to ambient free air	in free air	-	45	-	K/W

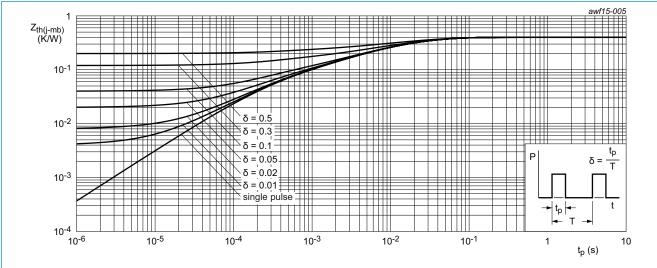
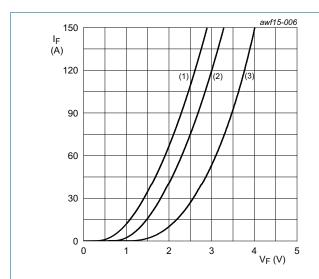


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static ch	aracteristics					
V _F f	forward voltage	I _F = 75 A; T _j = 25 °C; <u>Fig. 6</u>	-	2.8	3.3	V
		I _F = 75 A; T _j = 150 °C; <u>Fig. 6</u>	-	2.2	-	V
I _R	reverse current	V _R = 1200 V; T _j = 25 °C	-	-	250	μA
		V _R = 1200 V; T _j = 125 °C	-	-	2	mA
Dynamic	characteristics		'			
Q _r	reverse charge	$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_J = 25 \text{ °C}; Fig. 7$	-	1282	-	nC
		$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 7$	-	3729	-	nC
		$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 150 \text{ °C}; Fig. 7$	-	4608	-	nC
t _{rr}	reverse recovery time	$I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 100 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	-	85	ns
		$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_i = 25 \text{ °C}; Fig. 7$	-	113	-	ns
		$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 125 \text{ °C}; Fig. 7$	-	232	-	ns
		$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 150 \text{ °C}; Fig. 7$	-	265	-	ns
I _{RM}	peak reverse recovery current	$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 25 \text{ °C}; Fig. 7$	-	22.4	-	А
		I _F = 50 A; V _R = 400 V; dI _F /dt = 500 A/μs; T _i = 125 °C; <u>Fig. 7</u>	-	32	-	А
		$I_F = 50 \text{ A}; V_R = 400 \text{ V}; dI_F/dt = 500 \text{ A/}\mu\text{s};$ $T_j = 150 \text{ °C}; Fig. 7$	-	34.6	-	А
Avalanch	ne energy		1			
E _{AS}	non-repetitive avalanche energy	$I_R = 1.6 \text{ A}; T_{j(init)} = 25 \text{ °C}; L = 40 \text{ mH}$	50	-	-	mJ



 V_o = 1.727 V; R_s = 0.0106 Ω

(1) $T_j = 150 \,^{\circ}\text{C}$; typical values

(2) $T_j = 150$ °C; maximum values (3) $T_j = 25$ °C; maximum values

Fig. 6. Forward current as a function of forward voltage

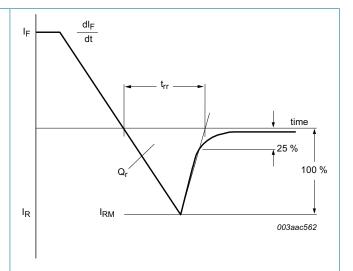
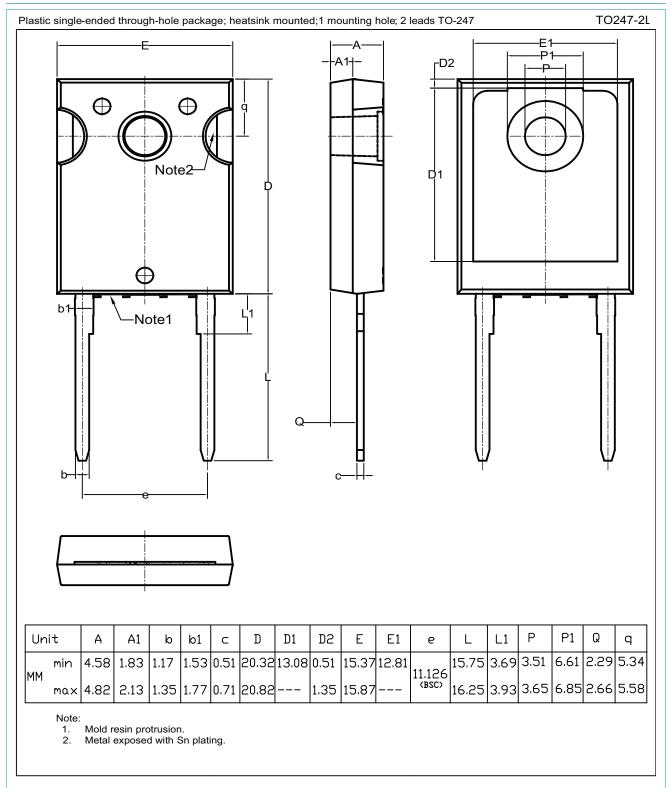


Fig. 7. Reverse recovery definitions; ramp recovery

11. Package outline



12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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